

# Measurement of Seebeck coefficient perpendicular to SiGe superlattice

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## Abstract

Seebeck coefficient is one of the key parameters to evaluate the performance of thermoelectric coolers. However, it is very difficult to directly measure Seebeck coefficient perpendicular to thin film devices because of the difficulty of creating a temperature gradient and measuring localized temperature and voltage change simultaneously. In this paper, a novel method is described and it is used to measure the Seebeck coefficient of SiGe superlattice material perpendicular to the layers<sup>1</sup>. Successful measurement was achieved by integrating a thin film metal wire as a temperature sensor and heat source on top of the SiGe superlattice micro coolers. Extensive thermoreflectance imaging characterization was performed to ensure uniform temperature distribution on top of the thin film device. Details of the experimental set-up and measurement technique are discussed. By analyzing the measured thermoelectric voltage for various device sizes and superlattice thickness, Seebeck coefficient of the superlattice material perpendicular to the layers is deduced.

## Introduction

In VLSI circuits, high heating power density is one of the bottlenecks that limits the reliability and performance of the chip in high-speed, high-density applications. Conventional bulk Bi<sub>2</sub>Te<sub>3</sub> coolers<sup>2</sup> have limited applications in microelectronic circuits due to low cooling power density and difficulty of integration and packaging<sup>3</sup>. Conventional Si or III-V based semiconductor materials have a low thermoelectric figure-of-merit and they are not suited for cooling application. There have been several excellent recent studies on BiTe-based thin film coolers with high thermoelectric figure-of-merit<sup>2</sup>. We are concentrating on SiGe based coolers for the possibility of direct integration with silicon circuits. Use of thermionic emission in heterostructure superlattices can improve the figure-of-merit by selective emission of hot electrons above potential barriers and by reducing the phonon heat conduction in multilayer materials. SiGe and SiGeC-based coolers have already demonstrated a cooling power density exceeding 500W/cm<sup>2</sup> and a maximum cooling of 4°C at room temperature.<sup>4</sup>

In this paper, we focus our study on the Seebeck coefficient perpendicular to SiGe superlattice layers. Although there are some papers on the cross-plan thermal conductivity, electrical conductivity of SiGe superlattice<sup>5,6,7,8</sup>. There are still very few papers on the experimental measurements of the Seebeck coefficient

perpendicular to the thin film because of its difficulty to measure the voltage and temperature change simultaneously.<sup>9,10</sup> We used an integrated thin film resistor both as a heater and a sensor on top of the SiGe superlattice microcooler. The processing was done using the standard semiconductor fabrication process<sup>11</sup>.

In a linear transport regime, the Seebeck coefficient is defined as the voltage produced across two points on a material divided by the temperature difference between them. This has an expression of  $S = \frac{\Delta V}{\Delta T}$ <sup>12</sup>. Seebeck

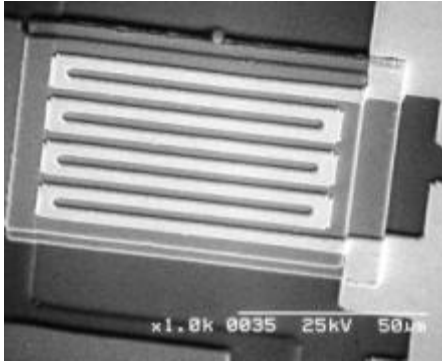
coefficient is the main parameter to evaluate performance of thermocouples. It is also the key parameter to calculate the ZT, the thermoelectric figure of merit, which has the expression of:

$$ZT = S^2T / \rho K_T \quad (\text{Eqn.1})$$

Where S: Seebeck coefficient; T: temperature;  $\rho$ : electrical resistivity;  $K_T$ : Thermal conductivity<sup>12</sup>.

## Experiments

The micro-cooler structure is based on cross-plane electrical transport theory. The main part of the cooler is a superlattice structure of 80Å Si/40 Å Si<sub>0.7</sub>Ge<sub>0.3</sub> grown at 500°C, doped with boron to about 5x10<sup>19</sup> cm<sup>-3</sup>. The buffer layer was grown on top of the silicon with the structure of 1µm SiGe<sub>0.1</sub> doped to 5x10<sup>19</sup> cm<sup>-3</sup> and 1µm SiGe<sub>0.1</sub>/SiGe<sub>0.15</sub>C<sub>0.005</sub>. Finally, the sample was capped with 250nm SiGe<sub>0.1</sub>, doped to approximately 2x10<sup>20</sup> cm<sup>-3</sup>. The SiGe/Si micro-coolers are fabricated with standard silicon integrated circuit technology. The cooler device areas were defined by etching mesas down to the SiGe buffer layer. Ti/Al/Ti/Au metallisation was made on top of the mesa and on the SiGe buffer layer next to the mesa for top and bottom contacts respectively. The size of the sample is ranging from 50x50µm to 100x100µm. Figure. 1 shows a scanning electron micrograph picture of this device.

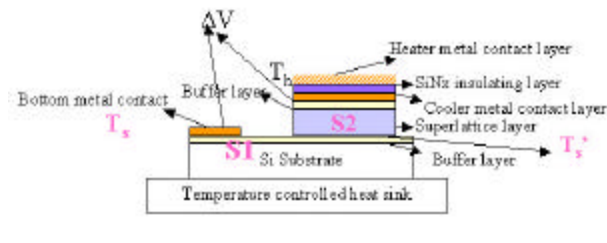


**Figure 1** The SEM picture of SiGe superlattice microcooler integrated with heater sensor

First resistance versus temperature of the heater sensor was calibrated. Four-wire measurement was used to reduce the effect of contact wires and pads. Then at a given heater power (fixed top layer temperature,  $T_h$ ), the voltage difference across the device  $\Delta V$  was measured. The bottom of the silicon substrate was maintained at the heat sink temperature ( $T_s$ ). It is important to note that the measured thermoelectric voltage  $\Delta V$  has a contribution from both the superlattice Seebeck coefficient and also the Si substrate Seebeck coefficient.

$$\Delta V = S1 \times (T_s' - T_s) + S2 \times (T_h - T_s') \quad (\text{Eqn. 2})$$

$S1$  is the Seebeck coefficient of bulk Silicon;  $T_s'$  is the temperature at the interface between the superlattice layer and substrate. If the temperature  $T_s'$  is equal to  $T_s$ , then the effective Seebeck coefficient equals to that of superlattice. However, this is not the case for our devices. We will see that the superlattice Seebeck coefficient  $S2$  could be easily derived by analyzing experimental results for different thin film layer thicknesses and device sizes. Bao Yang et al have used AC method to measure Seebeck coefficient of thin films<sup>13</sup>, the signal of our samples are large enough for an accurate DC measurements.



**Figure 2** Cross-section schematic of superlattice device (not to scale)

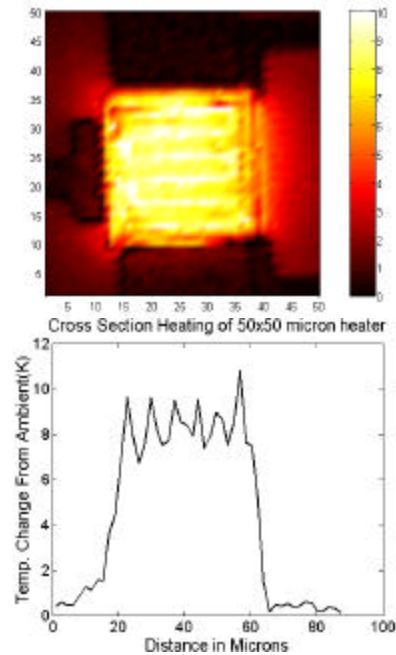
### Results and Discussion

The heater resistance changes linearly with temperature near 300K, so it was used as a temperature sensor on top of the superlattice device. The temperature sensor was

calibrated by measuring the resistance with very low excitation currents at different ambient temperatures. Variations of the resistance with temperature could be fitted well with a line, with an error less than 0.02%. The heater samples used in this experiments have an average of  $4 \times 10^3$

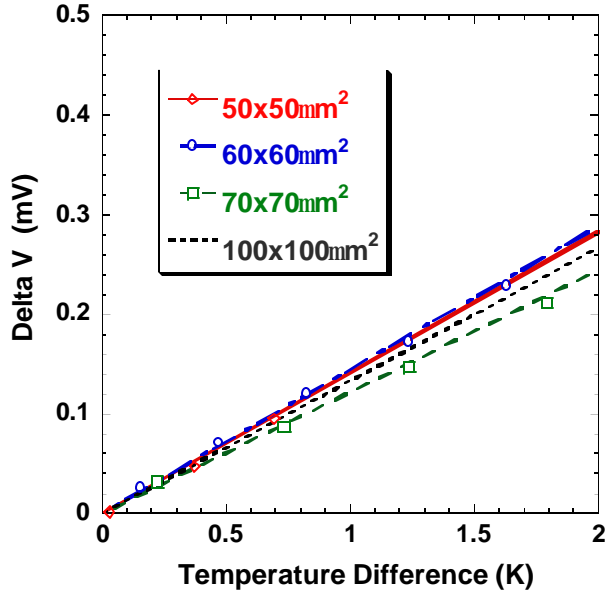
$\rho/C$  in a unit resistance  $(\frac{dR/dT}{R})$ . Subsequently

thermoreflectance imaging was used to measure the temperature distribution on top of the device when the heater was on. As it can be seen from Fig. 3, the heating was localized on top of the thin film device.



**Figure 3** Demonstration of localized heating of SiGe superlattice micro coolers

Figure 4 displays the voltage change across the sample as a function of the temperature gradient for all different size samples, ranging from  $50 \times 50 \mu\text{m}$  to  $100 \times 100 \mu\text{m}$ . The slope of the curve is the average Seebeck coefficient with contribution from superlattice and silicon substrate. It is known that seebeck coefficient is geometry independent thermodynamic property. This corresponds with the results in Figure 4, which shows size independent of effective seebeck coefficient. Table 1 summarizes the thermoelectric voltage measured in the experiments. It shows the sample  $\text{SiGe}_{0.2}\text{B}$  with  $3 \mu\text{m}$  superlattice thickness and doping concentration of  $5.7 \times 10^{19} \text{ cm}^{-3}$  has an average Seebeck coefficient of  $135.4 \mu\text{V}/^\circ\text{C}$ .



**Figure 4** Thermoelectric voltage versus temperature difference between top of the device and bottom contact

Sample size (μm×μm)	Effective Seebeck coefficient (μV/°C)
50x50	138±0.1
60x60	140.0±1.0
70x70	131.0±0.6
100x100	132.4±1.0
Average	135.4

**Table 1** Si<sub>0.7</sub>Ge<sub>0.3</sub> superlattice microcooler Seebeck coefficient data for different size samples

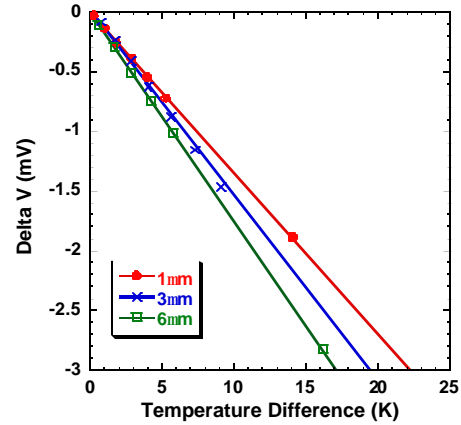
Venkatasubramanian's recent paper in Nature<sup>2</sup> reported the cooling performance is related to the thickness of the superlattice layer. To further investigate the influence of different superlattice thickness on the device property. We also measured the thermoelectric voltage for different superlattice thickness, 1μm, 3μm, and 6μm. The results were illustrated in . It can be seen that thicker the superlattice thickness, higher the measured thermoelectric voltage 135μV/°C, 154μV/°C and 174μV/°C for 1μm, 3μm and 6μm superlattice respectively. The increase of the thermoelectric voltage is due to the increase in the thermal resistance of the thin film device with respect to the substrate as superlattice becomes thicker. As illustrated in Figure 6 simplified thermal model of superlattice micro-cooler device, from the equation of

$$R_{th} = \frac{1}{b_{th}} * \frac{d}{A} \quad (\text{Eqn.3})$$

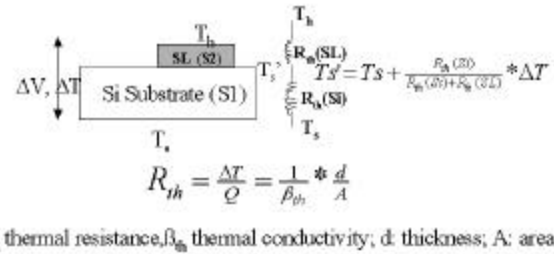
it is obvious to see R<sub>th</sub>(SL): thermal resistance superlattice is proportional to the uperlattice thickness d<sub>l</sub>. The change of R<sub>th</sub>(SL) directly influences T<sub>s</sub>':

$$T_s' = T_s + \frac{R_{th}(Si)}{R_{th}(Si)+R_{th}(SL)} * \Delta T \quad (\text{Eqn. 4})$$

And it causes the change of effective seebeck coefficient: S=[S2\*(Th-T<sub>s</sub>')+S1\*(T<sub>s</sub>'-T<sub>s</sub>)]/DT (Eqn.5)



**Figure 5** Comparison of seebeck coefficient with different superlattice thickness (fitted)



**Figure 6** Simplified thermal model of superlattice micro-cooler (This model assumes the thermal resistance of the SiN<sub>x</sub> and buffer layer is much smaller than the thermal resistance of the superlattice layer)

To calculate the actual Seebeck coefficient of superlattice, we need to know the T<sub>s</sub>', which is related with the thermal resistance of the device. In this calculation, thermal resistance was obtained experimentally by using equation:

$$R_{th} = \frac{\Delta T}{Q} \quad (\text{Eqn. 6})$$

ΔT is the temperature difference created, Q is the heat load on top of the device. The thermal resistance for a 100x100μm<sup>2</sup> device based on bulk silicon R<sub>th</sub>(Si) was 157.0 K/W, the measured thermal resistance of the device with different superlattice thickness were listed in Table 2. From the known of thermal resistance of bulk Silicon and that of the overall device (superlattice+substrate), the T<sub>s</sub>' - T<sub>s</sub> could be calculated by Eqn.4 assuming a temperature change of 10K. The ΔV of the device could be obtained by its effective Seebeck

coefficient. Then a pure superlattice of this structure S2 could be calculated by Eqn.2 with all the known data.

Table 2 lists all the calculation results and it showed an average seebeck coefficient of this structure superlattice is around  $217.6 \mu\text{V}/^\circ\text{C}$ .

SL thickness	$R_{th}$ (Device) (K/W)	$\Delta V$ (mV)	$T_s' - T_s$ (K)	S (SL) ( $\mu\text{V}/^\circ\text{C}$ )
1 $\mu\text{m}$	215.1	1.28	7.30	229.6 $\pm$ 10.0
3 $\mu\text{m}$	322.3	1.54	4.87	205.3 $\pm$ 10.5
6 $\mu\text{m}$	422	1.68	3.72	217.8 $\pm$ 8.2
Ave. SL seebeck coefficient	$217.6 \mu\text{V}/^\circ\text{C}$			

**Table 2** Calculation of superlattice thickness  
( Sample size 100x100 $\mu\text{m}$ )

### Conclusions

We showed that the integrated heater sensor on top of the thin films provides a convenient method to characterize the Seebeck of SiGe superlattice material. This will help further development and improvement of the performance of SiGe superlattice coolers.

Seebeck coefficient of  $\sim 217 \mu\text{V}/\text{K}$  was measured for Si/SiGe superlattice p-doped to  $5 \times 10^{19} \text{cm}^{-3}$ . The experimental results were verified by obtaining consistent results with various superlattice thickness (1-6 $\mu\text{m}$ ) and device sizes (2,500-10,000  $\mu\text{m}^2$ ).

### Acknowledgements

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